

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/26/2022

Details for "TP575901KC"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TP575901KC	SN	Level-NC-NC-NC	Ext-Mfg	KC 5	8.51x10.16x4.58	1566

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000119	0.007349	73	0.000008	0
Precious Metals	Gold	7440-57-5	1.619153	99.992651	999927	0.103392	1034
Sub-Total			1.619272	100	1000000	0.1034	1034
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.692497	86.999993	870000	0.108076	1081
Thermoplastics	Epoxy	85954-11-6	0.252902	13.000007	130000	0.016149	161
Sub-Total			1.945399	100	1000000	0.124225	1242
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	899.1	99.9	999000	57.412726	574127
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.9	0.1	1000	0.05747	575
Sub-Total			900	100	1000000	57.470197	574702
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	8.98	100	1000000	0.573425	5734
Sub-Total			8.98	100	1000000	0.573425	5734
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	549.453525	84.81	848100	35.08578	350858
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	33.688932	5.2	52000	2.151233	21512
Other Plastics and Rubber	Carbon Black	1333-86-4	1.360515	0.21	2100	0.086877	869
Thermoplastics	Epoxy	85954-11-6	63.361107	9.78	97800	4.045973	40460
Sub-Total			647.864079	100	1000000	41.369862	413699
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	5.620343	100	1000000	0.358891	3589
Sub-Total			5.620343	100	1000000	0.358891	3589
Total			1566.029093			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.